



Title of Change:	Gold wire to bare copper wire conversion for SOD523, SC88, SOT963 diode and transistor devices assembled in ON Semiconductor Leshan facility.	
Proposed first ship date:	21 May 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <Coleen.Long@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office or < Coleen.Long@onsemi.com>	
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>	
Change Part Identification:	At the expiration of this PCN devices will be assembled with 0.8mils bare Cu Wire at ON Semiconductor's existing Leshan facility. Products assembled with 0.8mils bare Cu Wire from the ON Semiconductor facility will have a Finish Goods Date Code of WW24, 2017 or greater.	
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Leshan, China	External Foundry/Subcon Sites: None
Description and Purpose:		
ON Semiconductor is notifying customers of its use of 0.8mils bare Cu wire for SOD523, SC88, SOT963 diode and transistor devices at ON Semiconductor's Leshan, China facility.		
Upon the expiration of this PCN, these devices will be built with 0.8mils bare Cu wire at the same site. Datasheet specifications and product electrical performance remain unchanged. Reliability Qualification and full electrical characterization over temperature has been performed.		
<i>Material to be changed</i>	Before Change Description	After Change Description
Wire	0.8mils gold wire	0.8mils copper wire



Qualification Plan:

Qual Vehicle Device: NSVMBD770DW1T1G/ SBAS16XV2T1G/ NSR0115CQP6T5G
PACKAGE: SOD523/ SC88 / SOT963

Test	Specification	Condition	Interval
PC	JESD22-A113	MSL 1 @ 260 °C	Before TC, AC, H3TRB, IOL
AC	JESD22-A102	121°C, 100% RH, ~15psig, unbiased	96 hrs
TC	JESD22-A104	Ta= - 65°C to +150°C	2000 cyc
H3TRB	JESD22-A101	85°C, 85% RH, V=80% rated V or 100V max.	2016 hrs
IOL	MIL-STD-750 (M1037)	Ta=+25°C, delta Tj=100°C On/off = 2 min	30000 cyc
HTRB	JEDS22- A108	Tj= max, V=100% rated V, 1008 Hrs	1008hrs
HTSL	JEDS22- A103	Temp.=165°C,no bias,2016hours	2016hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	-
SD	JSTD002	Ta = 245C, 10 sec	-

Estimated date for qualification completion: 26 February 2018

List of Affected Standard Parts:

Part Number	Qualification Vehicle
MBD330DWT1G	NSVMBD770DW1T1G
MBD770DWT1G	
RB751S40T1G	SBAS16XV2T1G
RB751S40T5G	
NSR0115CQP6T5G	NSR0115CQP6T5G



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
MBD330DWT1G		NSVMBD770WT1G
MBD770DWT1G		NSVMBD770WT1G
NSR0115CQP6T5G		NSR0115CQP6T5G
RB751S40T1G		SBAS16XV2T1G
RB751S40T5G		SBAS16XV2T1G